

# HOSTAFORM® C 13031 10/9022

## HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 04-002 POM copolymer Easy flowing Injection molding type like C 13021, but with higher strength, rigidity and hardness over the entire permissible temperature range for HOSTAFORM; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Hostaform® C 13031 10/9022 has been specially formulated for laser welding applications. Ranges of applications: For molded parts with higher requirements to strength, rigidity und hardness.

### Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

### Rheological properties

Melt volume-flow rate	12 cm <sup>3</sup> /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

### Typical mechanical properties

Tensile modulus	3100 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	70 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8 %	ISO 527-1/-2
Nominal strain at break	20 %	ISO 527-1/-2
Flexural modulus	3000 MPa	ISO 178
Tensile creep modulus, 1h	2750 MPa	ISO 899-1
Tensile creep modulus, 1000h	1450 MPa	ISO 899-1
Charpy impact strength, 23 °C	120 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy impact strength, -30 °C	120 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23 °C	6 kJ/m <sup>2</sup>	ISO 179/1eA
Charpy notched impact strength, -30 °C	6 kJ/m <sup>2</sup>	ISO 179/1eA
Ball indentation hardness, H 358/30	156 MPa	ISO 2039-1
Poisson's ratio	0.37 <sup>[C]</sup>	

[C]: Calculated

### Thermal properties

Melting temperature, 10 °C/min	170 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	112 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2

### Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Electric strength	35 kV/mm	IEC 60243-1

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### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m <sup>3</sup>	ISO 1183

### Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa

### Characteristics

Processing Injection Moulding

### Additional information

Injection molding

### Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

### Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Melt temperature 190-210 °C  
Mould temperature 80-120 °C

### Postprocessing

Conditioning e.g. moisturizing is not necessary.